



SMN-315-ARP7
W13.90xD11.20xH1.25

PIN 数(Number of contacts) : 6+1PIN

耐电压(Withstand voltage) : 500V AC for 1 min

操作方式(Operation mode): 自弹式/PUSH PUSH

操作寿命(Operation life): 5,000 Cycles Min

温度范围(Operating temp): -40°C TO +80°C

焊接温度(Welding temperature): 260±5° 5s

额定负荷(Rated load): 0.5A PERP IN.

焊接方式(Welding mode): 贴片式/SMT

接触电阻(Contact resistance): 100mΩ max.

包装方式(Packaging method): 卷带/Tape & Reel (TR)

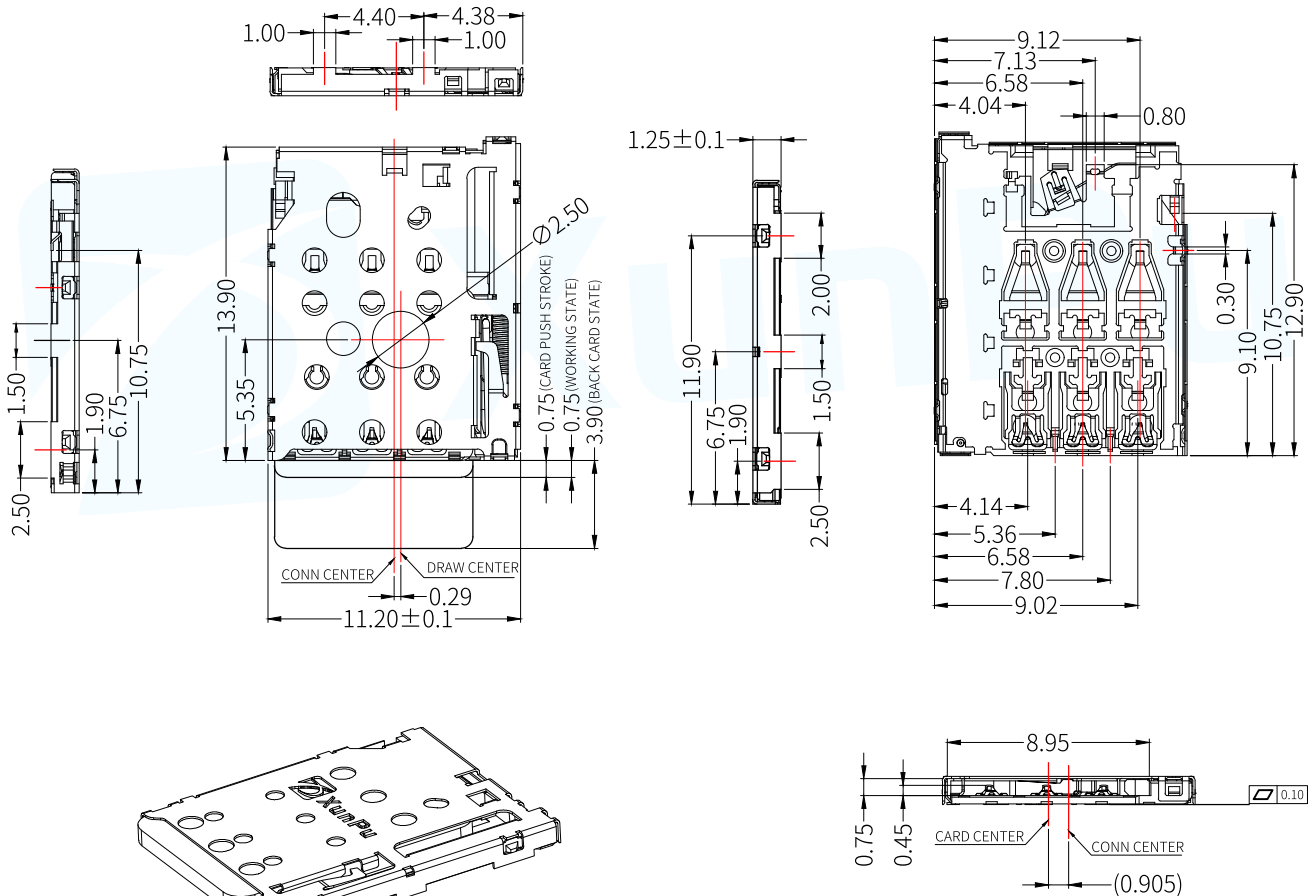
绝缘电阻(Insulation resistance): 1000MΩ min.

最小包装(Minimum packing): 2,000/PCS

外形尺寸 (UNIT:MM) / Size Chart

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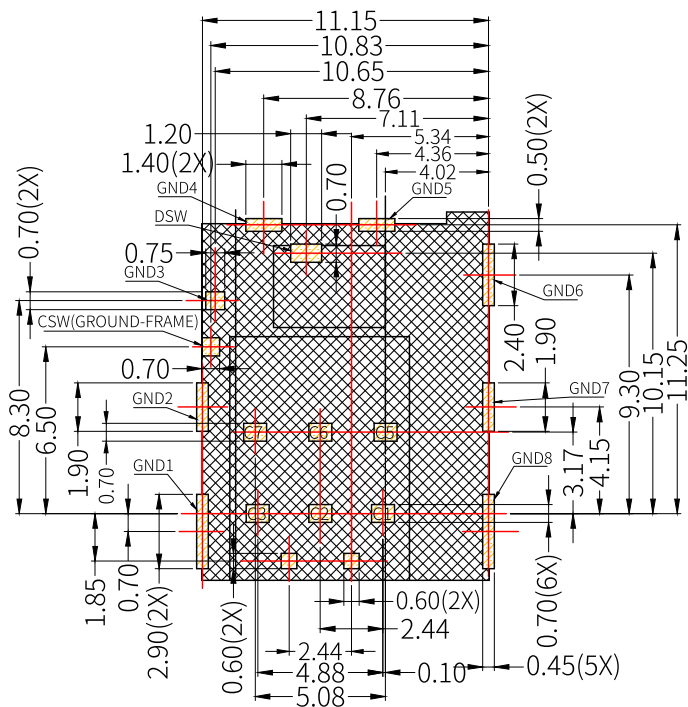
更多资料请参考技术选型档!



ITEM	PART NAME	MATERIAL	DESCRIPTION
1	HOUSING	LCP	GLASS FILLED(OR EQUAL),UL 94V-0,BLACK
2	TERMINAL	C5240-SH T=0.10	GOLD PATED ON CONTACT AREA"A" SEE "PLATED CODE NOTE" GOLD FLASH PLATED ON CONTACT AREA"B" AND SOLDER TAIL ATEA NICKEL 50~150u" UNDER PLATED OVER ALL
3	SHELL	SUS301-H T=0.10	GOLD FLASH PLATED ON SOLDER TAIL AREA NICKEL 30~100u" UNDER PLATED OVER ALL
4	SLIDE	PA46	GLASS FILLED(OR EQUAL),UL 94V-0,BLACK
5	SPRING	SUS	NO PLATING
6	HOOK	SUS304	NO PLATING

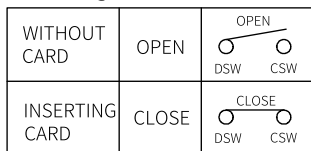
NOTES

- 1.FINISH
- 1-1.CONTACT:
 - CONTACT AREA: Au" 1~3U" Min
 - GOLD FLASH PLATING ON SOLDER AREA
- 1-2.SHELL:
 - SOLDER AREA: GOLD FLASH

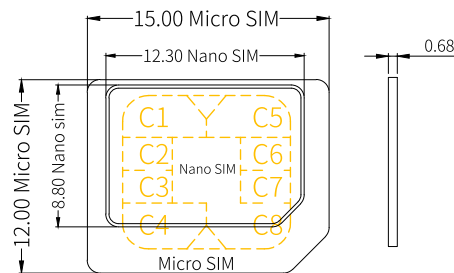


PCB焊盘区(PAD AREA)
 禁区(KEEP OUT AREA)
 RECOMMENDED PCB LAYOUT
 GENERAL TOLERANCE ±0.05

Circuit Diagram for Detect Switch



NANO SIM



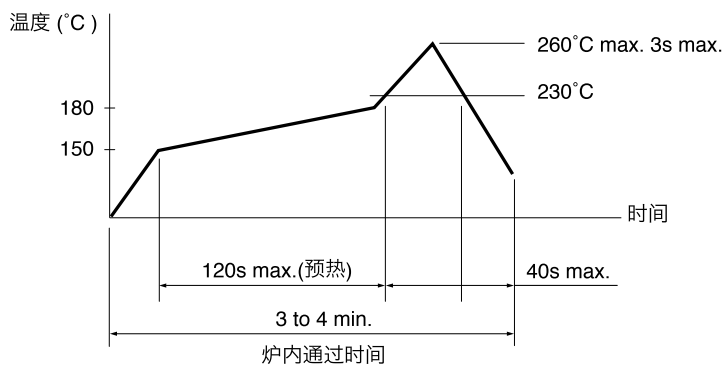
引脚定义/Pin Definition

SIM PIN ASSIGNMENT			
PIN#	NAME	TYPE	DESCRIPTION
C1	供电电压	1	VCC
C2	重置	1	RST
C3	时钟	1	CLK
C4	保留项	1	Reserved
C5	接地	1	GND
C6	程序电压	1	VPP
C7	输入输出	1	I/O
C8	保留项	1	Reserved

焊接条件 / Welding conditions

回流焊/Reflow soldering

适用表面贴装型产品/Applicable to surface mount products
 温度分布/Temperature distribution



注:

1. 加热方式:以远红外线上下加热方式。
2. 温度测量:用Φ0.1~0.2的 CA(K)或 CC(T)测量位置在焊接连接部(锡/铜箔面)。
3. 固定方式:采用耐热胶带。

手焊式/Hand welding

项目/Project	条件/condition
焊接温度 Welding temperature	350°C max.
持续焊接时间 Continuous welding time	3s max.
焊剂斗容量 Flux bucket capacity	60W max.

浸焊式/Immersion soldering

项目/Project	条件/condition
助焊剂附着量 Flux adhesion	不附着于零部件贴装面的程度 Not attached to the mounting surface of components
预热温度 Preheating temperature	印刷电路板焊接面的周围温度 100°C max. The temperature around the welding surface of PCB is 100 °C max
预热温度时间 Preheat temperature time	60s max.
焊接温度 welding temperature	260°C max.
焊接浸渍时间 Welding immersion time	5s max.
焊接次数 Welding times	2 times max.